Unit in mm

TOSHIBA Photocoupler GaAs Ired & Photo-Transistor

TLP731,TLP732

Office Machine
Household Use Equipment
Solid State Relay
Switching Power Supply

The TOSHIBA TLP731 and TLP732 consist of a photo-transistor optically coupled to a gallium arsenide infrared emitting diode in a six lead plastic DIP package.

TLP732 is no-base internal connection for high-EMI environments.

- Collector-emitter voltage: 55V (min.)
- Current transfer ratio: 50% (min.)

Rank GB: 100% (min.)

- UL recognized: UL1577, file No. E67349
- BSI approved: BS EN60065: 2002

Certificate No. 8877 BS EN60950-1: 2002

Certificate No. 8878

Isolation voltage: 4000V_{rms} (min.)

Option (D4) type

VDE approved: DIN EN 60747-5-2,

Certificate No. 40009302

Maximum operating insulation voltage: 630VpK Highest permissible over voltage: 6000VpK

(Note) When a EN 60747-5-2 approved type is needed, please designate the "Option (D4)"

		7.62mm pich	10.16mm pich
		standard type	(LF2) type
•	Creepage distance	7.0mm (min.)	8.0 mm (min.)
	Clearance	: 7.0 mm (min.)	8.0 mm (min.)
	Insulation thickness	: 0.5 mm (min.)	0.5 mm (min.)

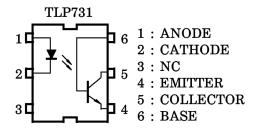
0.6 5 4 0.6 7.62 ± 0.25 7.62 ± 0.25 0.25 0.5 2.54 7.85~8.80

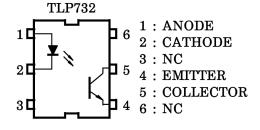
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Weight: 0.35 g

TOSHIBA

Pin Configurations (top view)





2007-10-01



Absolute Maximum Ratings (Ta = 25°C)

	Characteristic	Symbol	Rating	Unit
	Forward current	lF	60	mA
	Forward current derating (Ta ≥ 39°C)	ΔI _F / °C	-0.7	mA / °C
	Peak forward current (100µs pulse, 100pps)	I _{FP}	1	Α
LED	Power dissipation	P _D	100	mW
	Power dissipation derating (Ta ≥ 25°C)	ΔP _D / °C	-1.0	mW / °C
	Reverse voltage	V_{R}	5	V
	Junction temperature	Tj	125	°C
	Collector-emitter voltage	V _{CEO}	55	V
	Collector-base voltage (TLP731)	V _{CBO}	80	V
	Emitter–collector voltage	V _{ECO}	7	V
Detector	Emitter-base voltage (TLP731)	V _{EBO}	7	V
Dete	Collector current	IC	50	mA
	Power dissipation	PC	150	mW
	Power dissipation derating (Ta ≥ 25°C)	ΔP _C / °C	-1.5	mW / °C
	Junction temperature	Tj	125	°C
Storag	e temperature range	T _{stg}	-55~125	°C
Operat	ing temperature range	T _{opr}	-55~100	°C
Lead soldering temperature (10s)		T _{sol} 260		°C
Total package power dissipation		P _T	250	mW
Total p	ackage power dissipation derating (Ta ≥ 25°C)	ΔP _T / °C	-2.5	mW / °C
Isolatio	on voltage (AC, 1min., R.H.≤ 60%)	BVS	4000	V _{rms}

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Recommended Operating Conditions

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	V _{CC}	_	5	24	V
Forward current	lF	_	16	25	mA
Collector current	IC	_	1	10	mA
Operating temperature	T _{opr}	-25	_	85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.



Individual Electrical Characteristics (Ta = 25°C)

	Characteristic		Symbol	Test Condition	Min.	Тур.	Max.	Unit
	Forward voltage		V_{F}	I _F = 10mA	1.0	1.15	1.3	V
ED	Reverse current		I _R	V _R = 5V	_	_	10	μΑ
	Capacitance		C _T	V = 0, f = 1MHz	_	30	_	pF
	Collector–emitter breakdown voltage		V _{(BR)CEO}	I _C = 0.5mA	55	_	_	V
	Emitter–collector breakdown voltage		V _{(BR)ECO}	I _E = 0.1mA	7	_	-	V
	Collector-base breakdown voltage (1	TLP731)	V _{(BR)CBO}	I _C = 0.1mA	80	_	_	V
	Emitter-base breakdown voltage (1	TLP731)	V _{(BR)EBO}	I _E = 0.1mA	7	_	_	V
Detector	Collector dark current	lono	V _{CE} = 24V	_	10	100	nA	
Dete	Collector dark current		I _{CEO}	V _{CE} = 24V, Ta = 85°C	_	2	50	μA
	Collector dark current (1	TLP731)	I _{CER}	V_{CE} = 24V, Ta = 85°C R _{BE} = 1M Ω	_	0.5	10	μA
	Collector dark current (TLP731) ICBO	I _{CBO}	V _{CB} = 10V	ı	0.1	ı	nA	
	DC forward current gain (1	TLP731)	h _{FE}	V _{CE} = 5V, I _C = 0.5mA	_	400	_	_
	Capacitance collector to emitter		C _{CE}	V = 0, f = 1MHz	_	10	1	pF

Coupled Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Current transfer ratio	I _C / I _F	I _F = 5mA, V _{CE} = 5V	50	_	600	%
Current transier ratio	IC / IF	Rank GB	100	_	600	
Saturated CTR	I _C / I _{F (sat)}	I _F = 1mA, V _{CE} = 0.4V Rank GB	_	60	_	%
Saturated CTK			30	_	_	
Base photo-current (TLP731)	I _{PB}	I _F = 5mA, V _{CB} = 5V	-	10	_	μA
		I _C = 2.4mA, I _F = 8mA	_	_	0.4	
Collector–emitter saturation voltage	V _{CE} (sat)	I _C = 0.2mA, I _F = 1mA	_	0.2	_	V
, and the second		Rank GB	_	_	0.4	



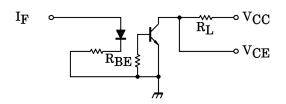
Isolation Characteristics (Ta = 25°C)

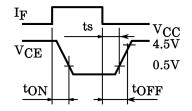
Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Capacitance (input to output)	CS	V _S = 0, f = 1MHz	_	0.8	_	pF
Isolation resistance	R _S	V _S = 500V	1×10 ¹²	10 ¹⁴	_	Ω
	BVS	AC, 1 minute	4000	_	_	\/
Isolation voltage		AC, 1 second, in oil	_	10000	_	V _{rms}
		DC, 1 minute, in oil	_	10000	_	V _{dc}

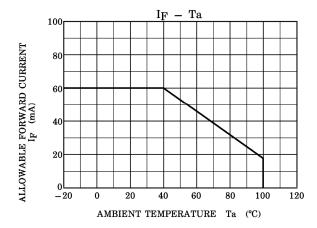
Switching Characteristics (Ta = 25°C)

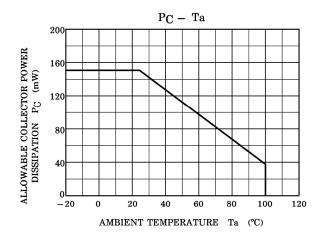
Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Rise time	t _r		_	2	_	μs
Fall time	t _f	V _{CC} = 10V, I _C = 2mA	_	3	_	
Turn-on time	t _{on}	$R_L = 100\Omega$	_	3	10	
Turn-off time	t _{off}		_	3	10	
Turn-on time	t _{ON}	R_L = 1.9kΩ (Fig.1) R_{BE} = open V_{CC} = 5V, I_F = 16mA	_	2	_	
Storage time	ts		_	15	_	μs
Turn-off time	t _{OFF}		_	25	_	
Turn-on time	t _{ON}	$R_L = 1.9k\Omega$ (Fig.1) $R_{BE} = 220k\Omega$ (TLP731) $V_{CC} = 5V$, $I_F = 16mA$	_	2	_	
Storage time	ts		_	12	_	μs
Turn-off time	t _{OFF}		_	20	_	

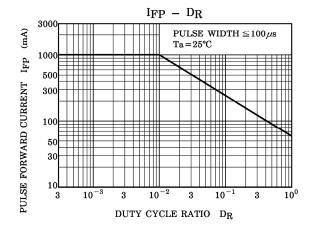
Fig. 1 Switching time test circuit

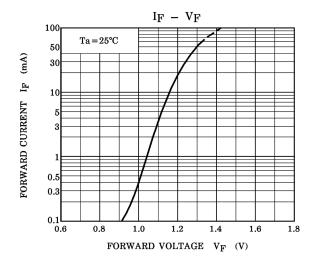


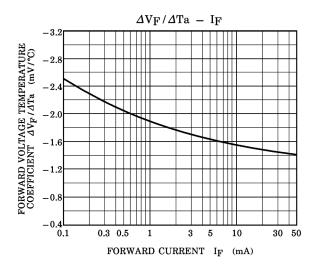


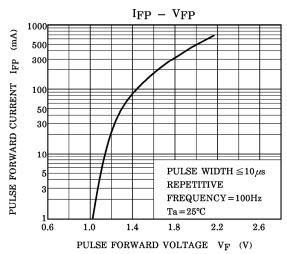


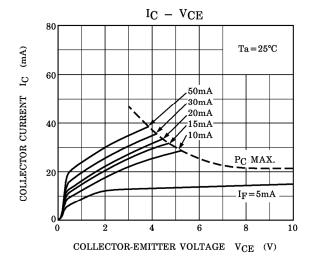


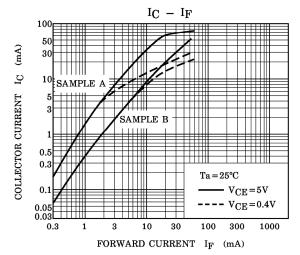


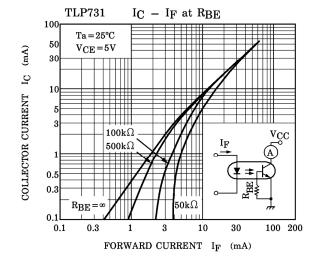


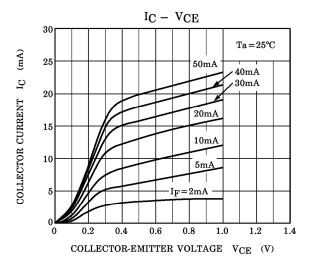


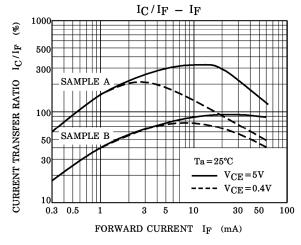


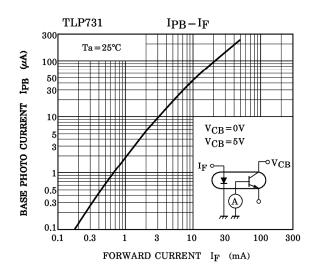




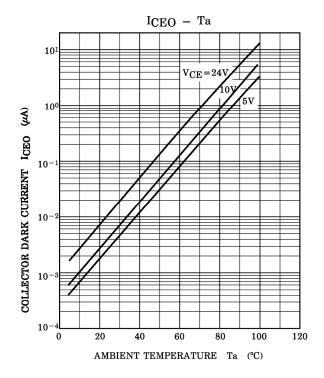


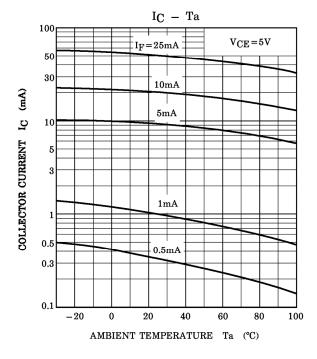


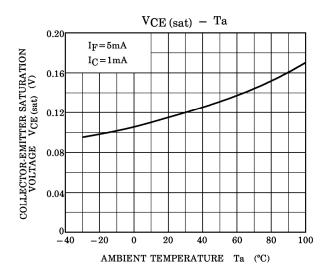


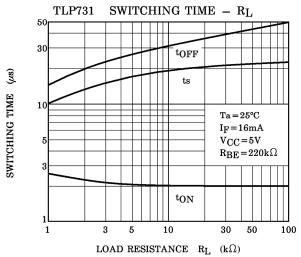


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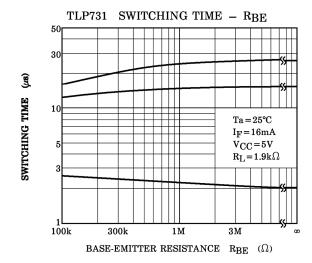


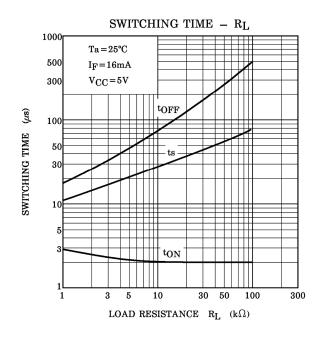






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